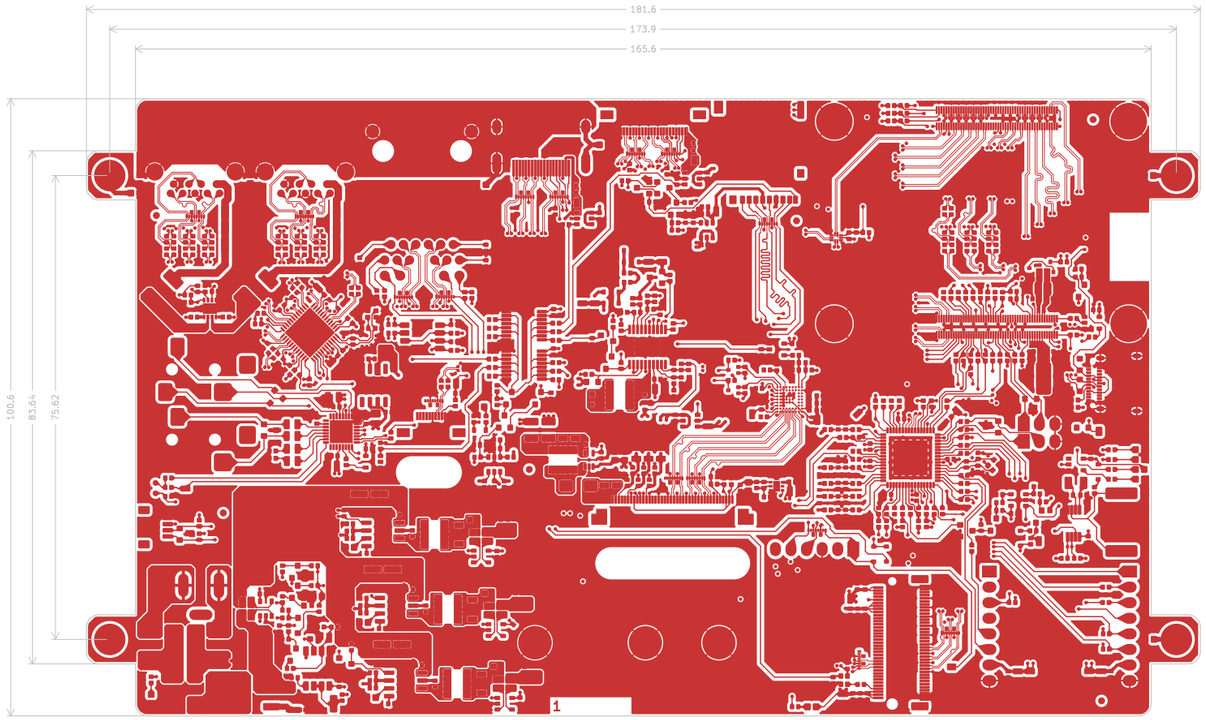


BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

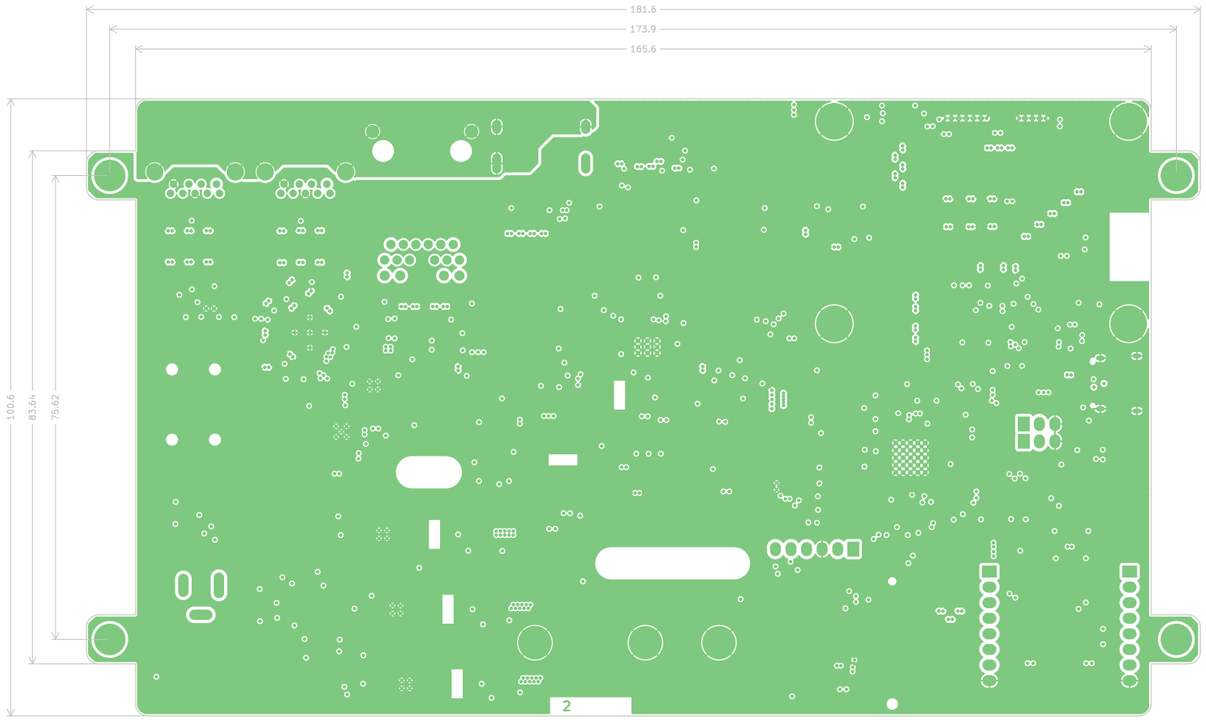
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 1 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

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Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

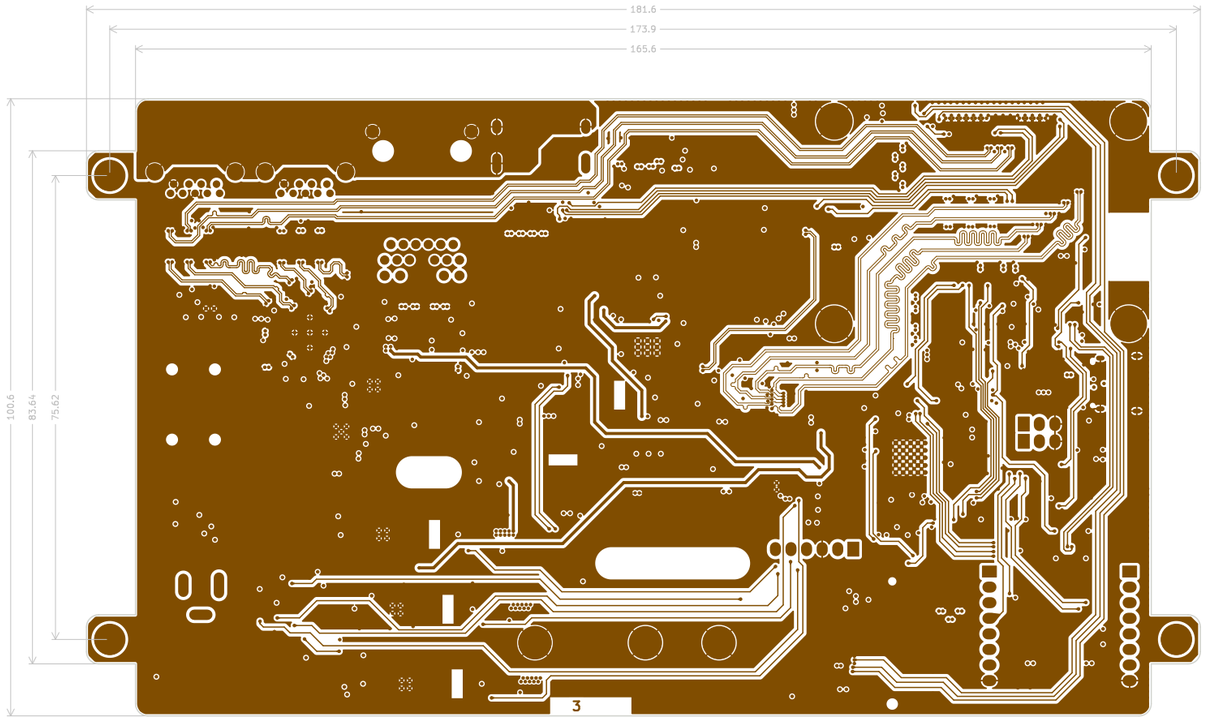
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 2 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

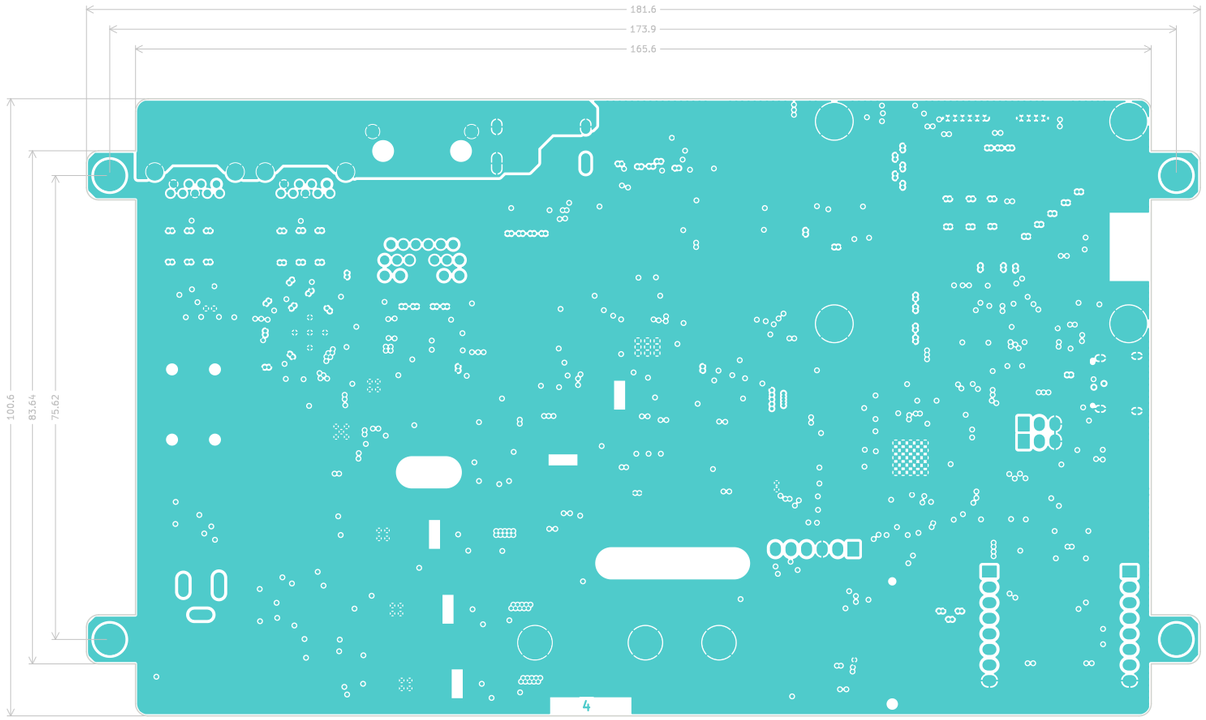
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 3 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

    Total unplated holes count 12
```

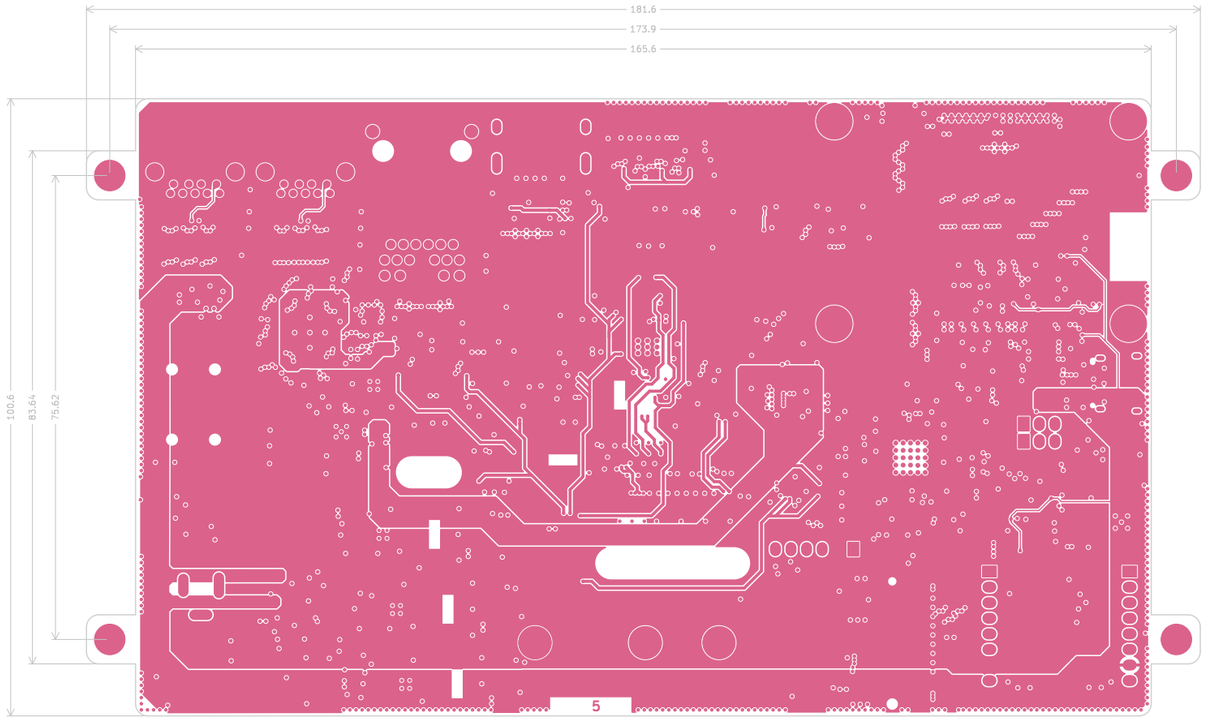
Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2

KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 4 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

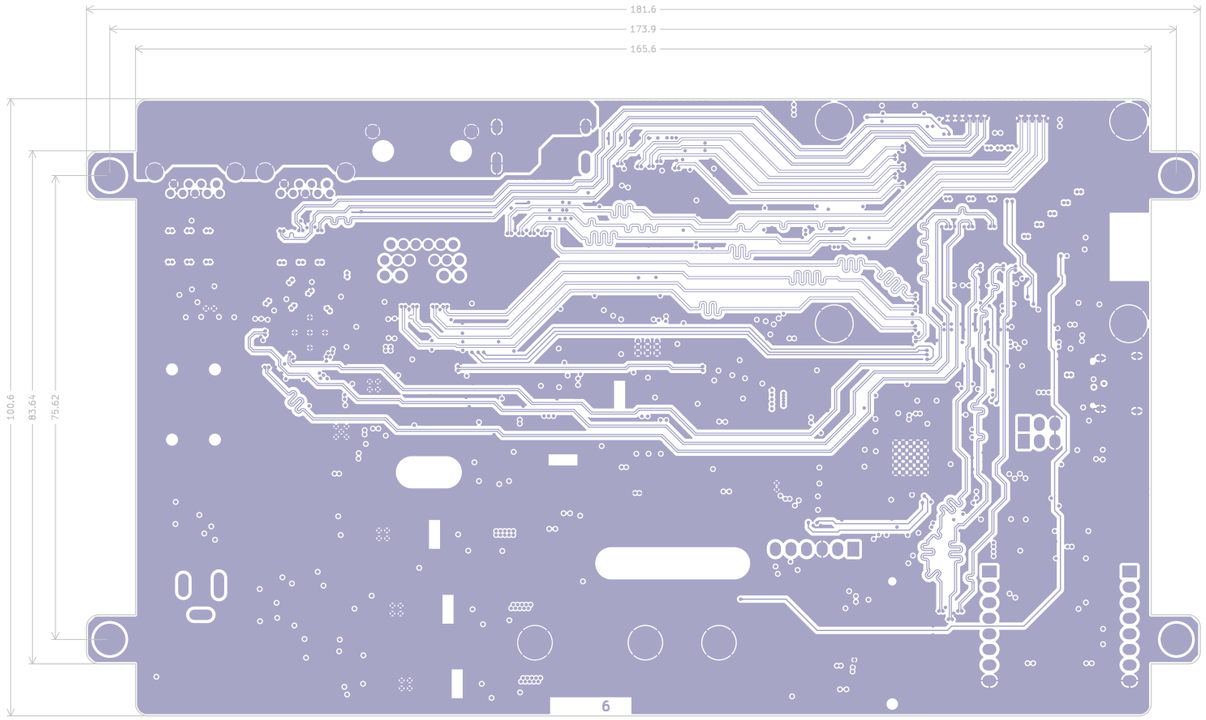
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 5 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

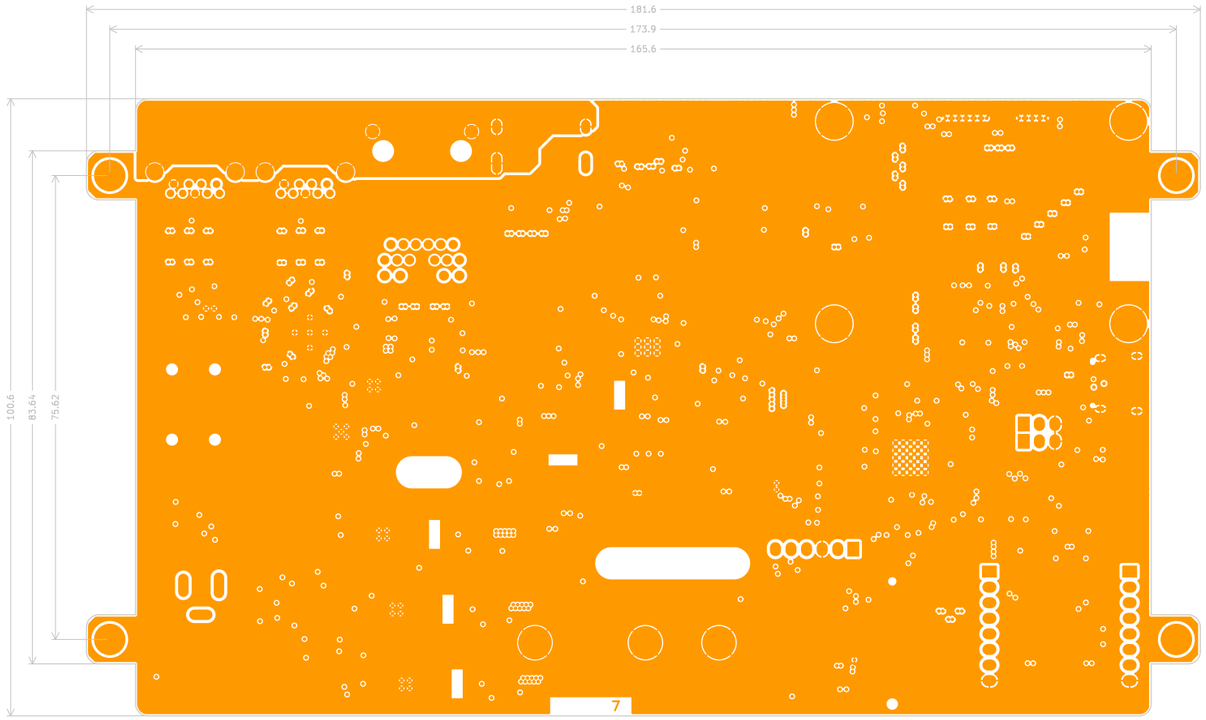
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 6 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

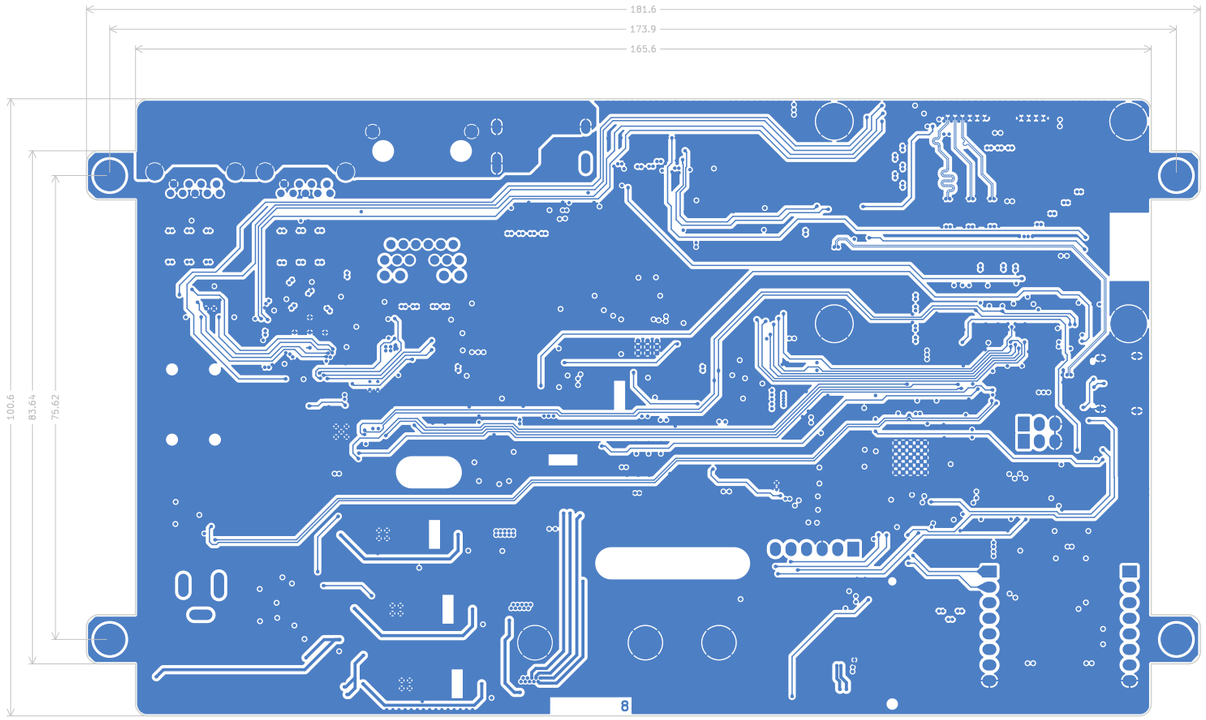
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

		Sheet Size: A3
Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet: 7 of 15
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Status: Review
Date: 2026-02-15	BOM:	Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

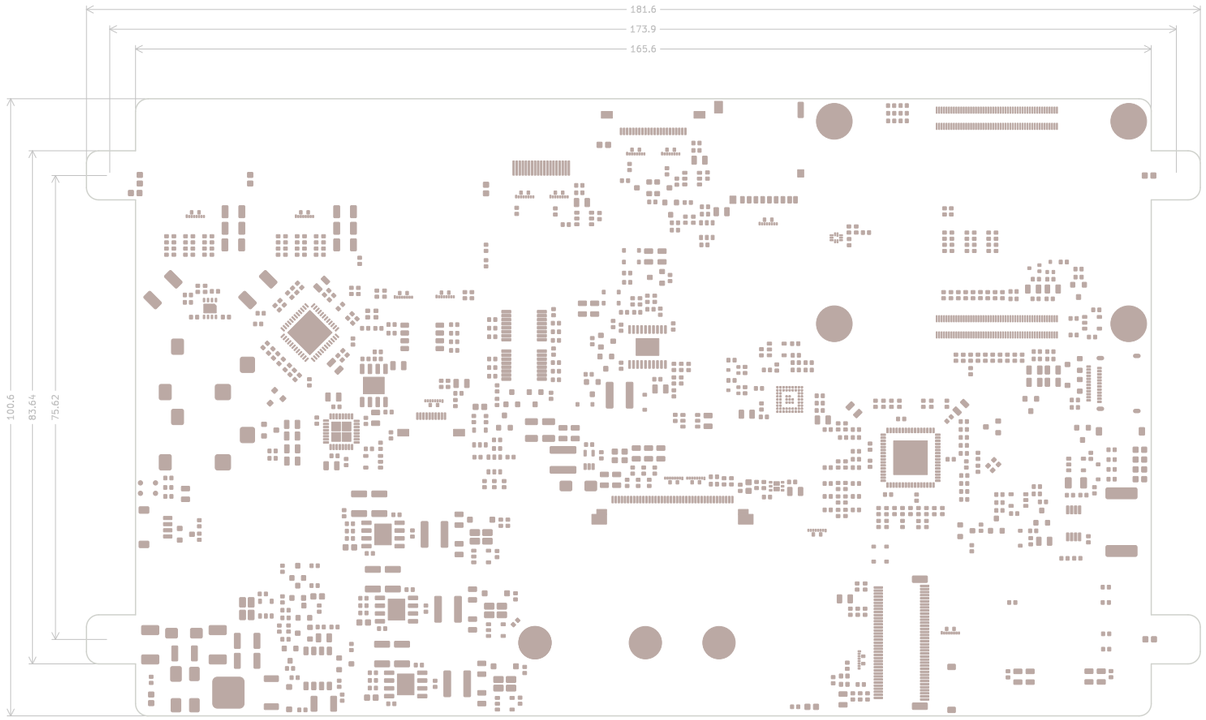
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

		Sheet Size: A3
Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet: 8 of 15
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Status: Review
Date: 2026-02-15	BOM:	Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

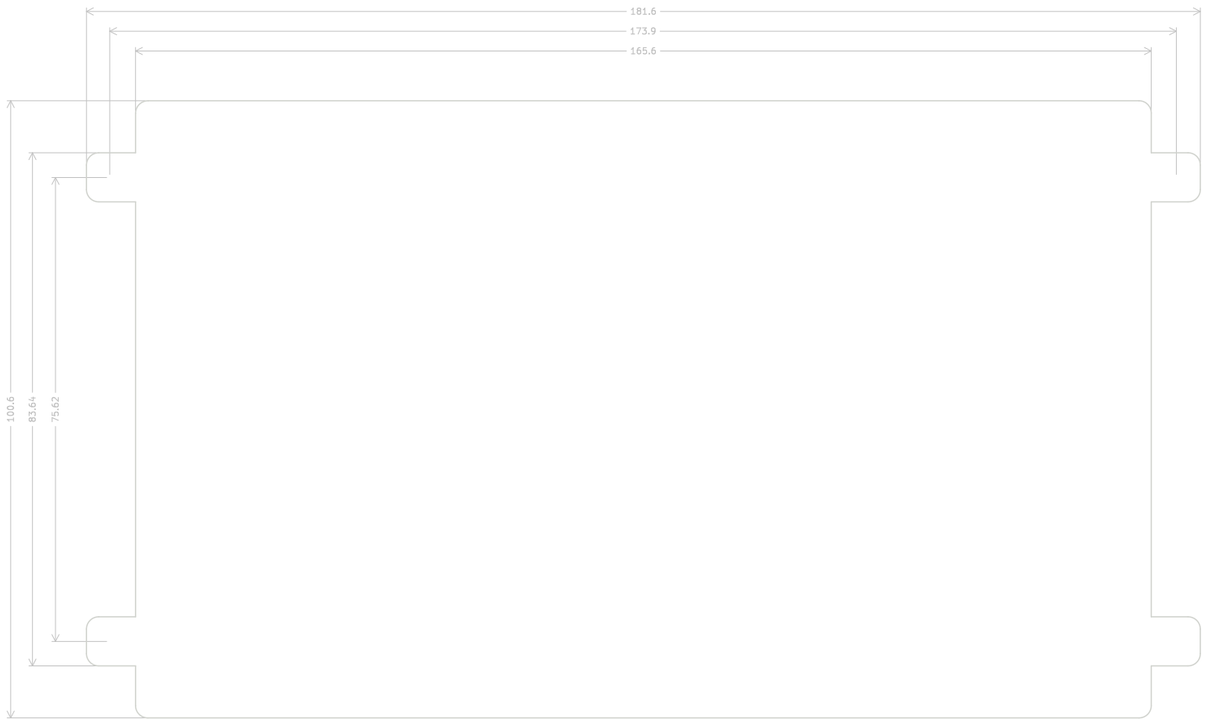
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 9 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

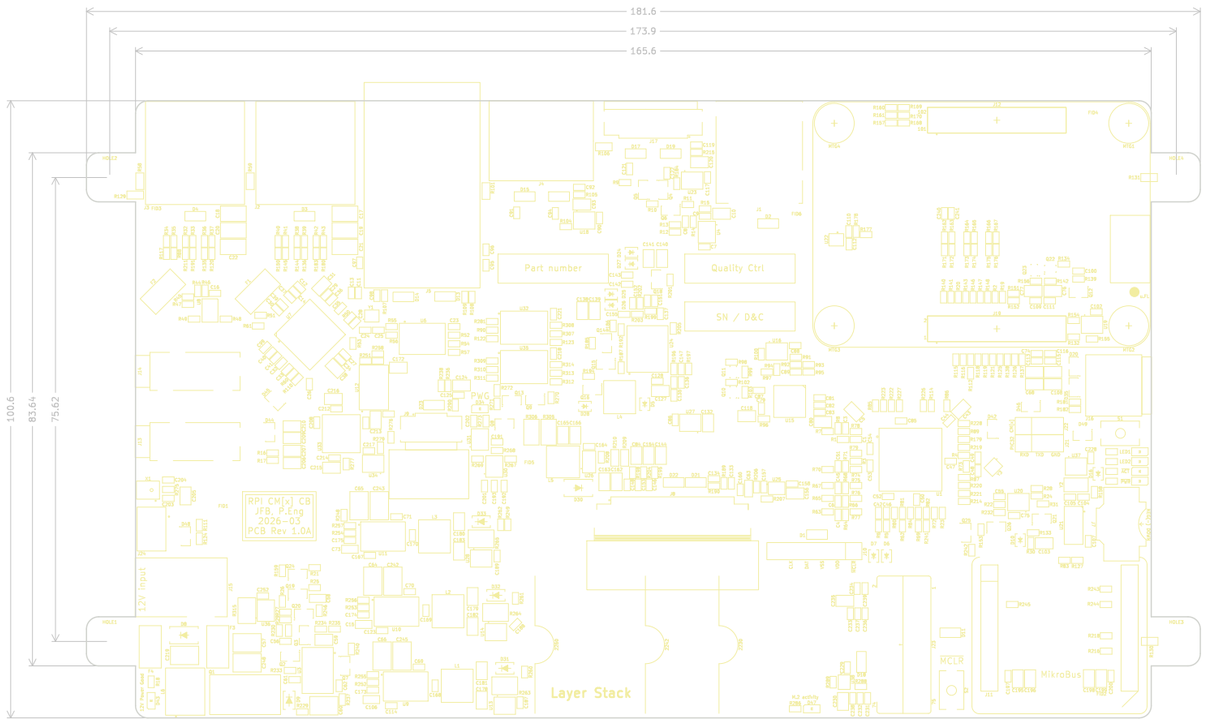
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 10 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    ==============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    ==============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

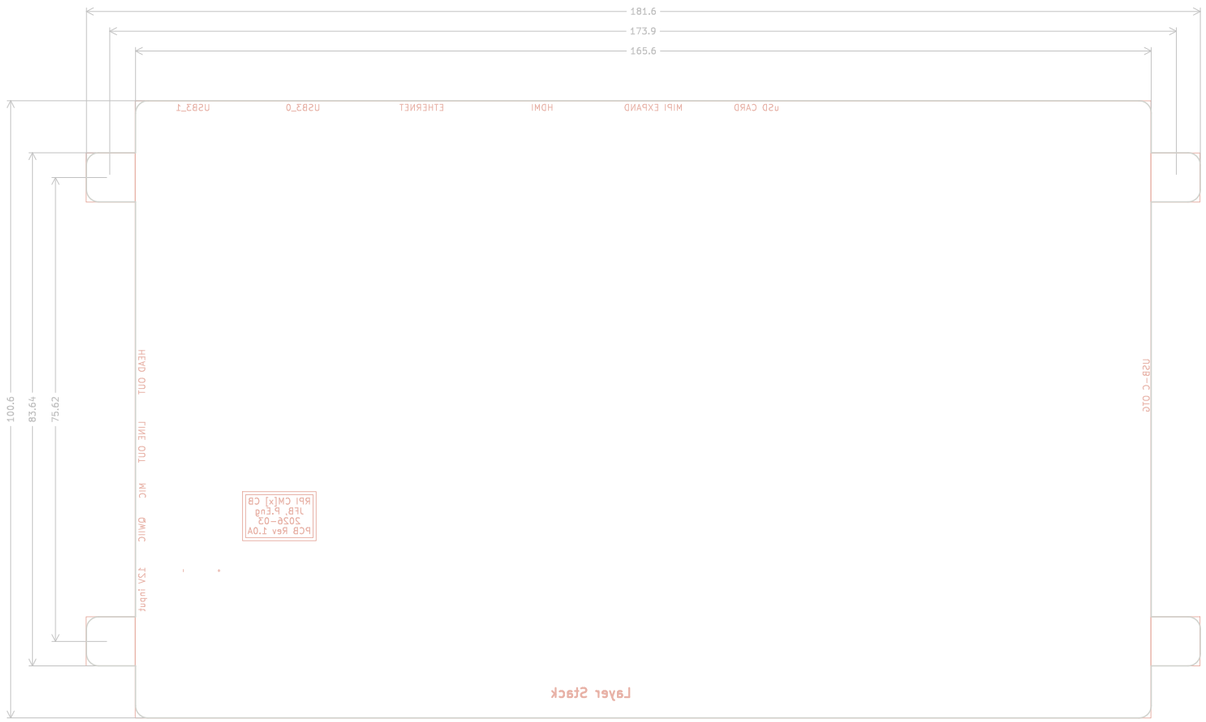
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 11 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

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Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

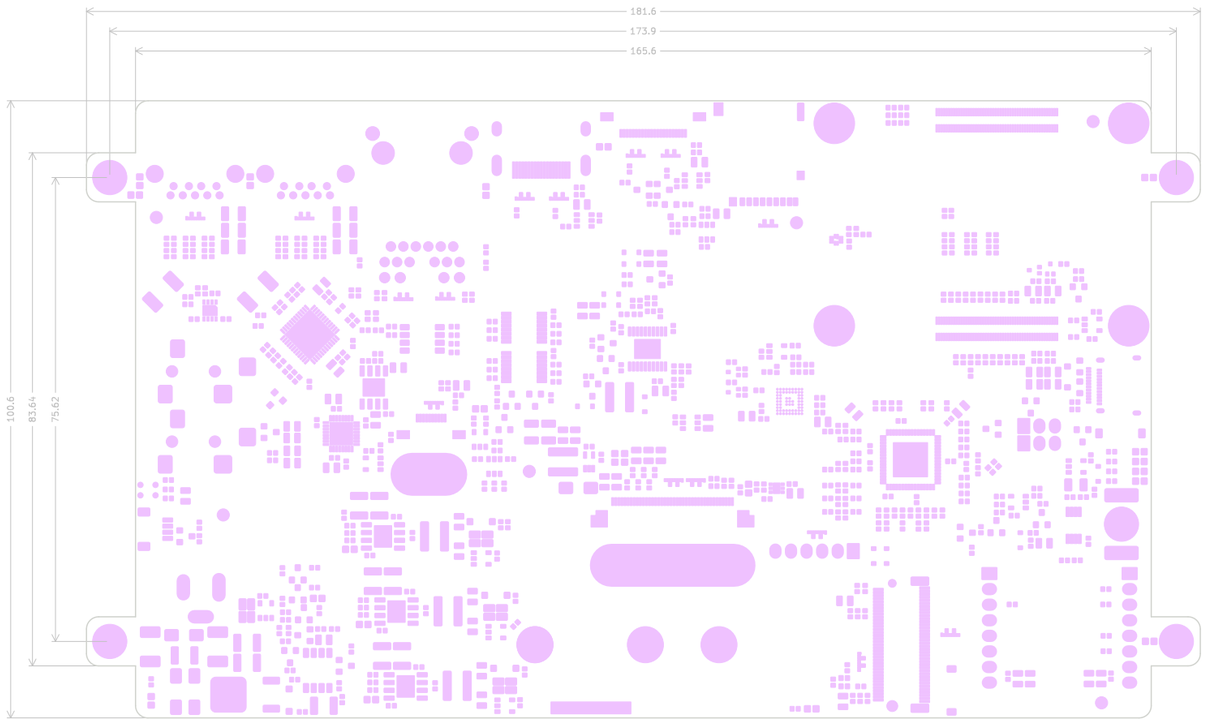
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 12 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

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Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    ================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    ================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 13 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A

BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.25 mm	Not specified	4.5	0.02
In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =============================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
    T9  1.100mm  0.0433"  (28 holes)
    T10  1.570mm  0.0618"  (2 holes)
    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =============================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

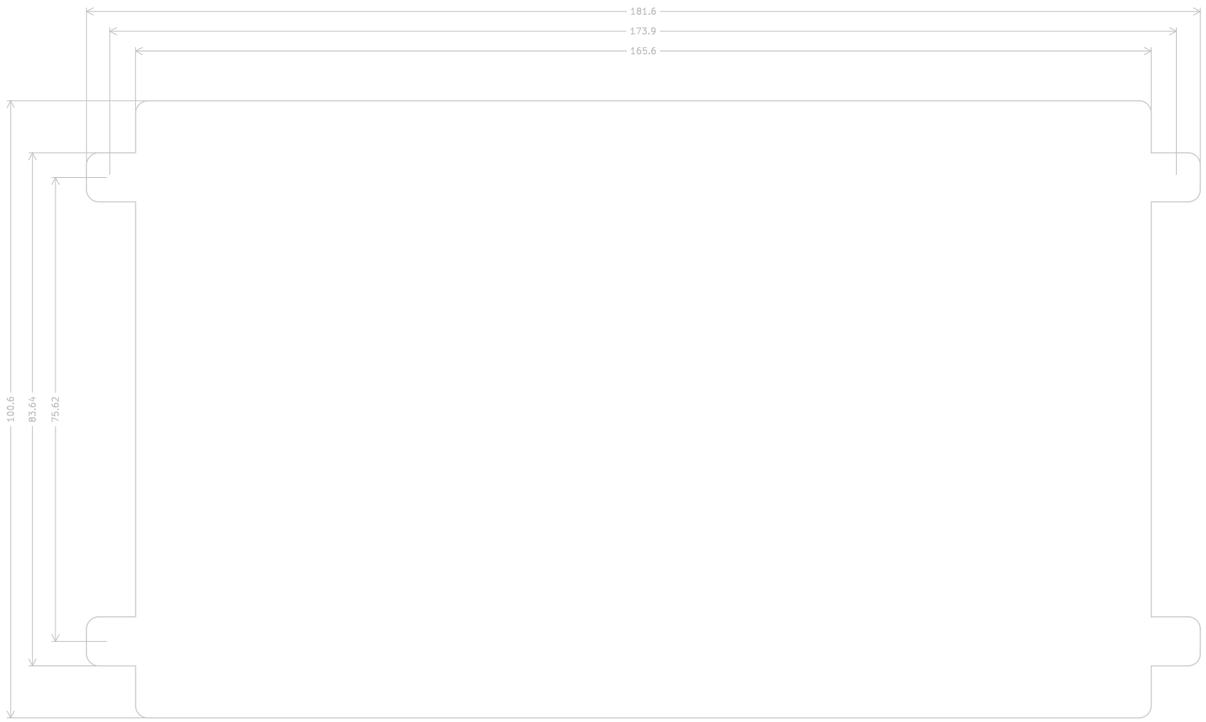
    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 14 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.6560 mm
Board overall dimensions:	181.6000 mm x 100.6000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.1500 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
In1.Cu	copper		0.03 mm		1	0
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In2.Cu	copper		0.03 mm		1	0
Dielectric 3	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In3.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.25 mm	Not specified	4.5	0.02
In4.Cu	copper		0.03 mm		1	0
Dielectric 5	prepreg	FR4	0.218 mm	Not specified	4.5	0.02
In5.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.25 mm	Not specified	4.5	0.02
In6.Cu	copper		0.03 mm		1	0
Dielectric 7	prepreg	FR4	0.109 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.001 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

```
Drill report for rpi_cm4_cm5_CarrierBoard.kicad_pcb
Created on 2026-02-15T12:01:54-0500

Drill file 'rpi_cm4_cm5_CarrierBoard-PTH.drl' contains
    plated through holes:
    =================================================================
    T1  0.200mm  0.0079"  (1489 holes)
    T2  0.200mm  0.0079"  (30 holes)
    T3  0.330mm  0.0130"  (34 holes)
    T4  0.500mm  0.0197"  (4 holes)  (with 4 slots)
    T5  0.700mm  0.0276"  (21 holes)  (with 3 slots)
    T6  0.890mm  0.0350"  (12 holes)
    T7  0.900mm  0.0354"  (4 holes)  (with 4 slots)
    T8  1.020mm  0.0402"  (4 holes)
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    T11  2.300mm  0.0906"  (4 holes)
    T12  3.000mm  0.1181"  (8 holes)
    T13  3.800mm  0.1496"  (4 holes)

    Total plated holes count 1644


Drill file 'rpi_cm4_cm5_CarrierBoard-NPTH.drl' contains
    unplated through holes:
    =================================================================
    T1  0.650mm  0.0256"  (2 holes)  (with 1 slot)
    T2  1.100mm  0.0433"  (1 hole)
    T3  1.600mm  0.0630"  (1 hole)
    T4  1.700mm  0.0669"  (4 holes)
    T5  3.300mm  0.1299"  (2 holes)
    T6  5.000mm  0.1969"  (2 holes)  (with 2 slots)

    Total unplated holes count 12
```

Revision	Change Order

Designed by: Jean-Francois Bilodeau
P.Eng #6022173
203-1690 rue des quatre-saisons
Sherbrooke, Canada, J1E0N2
KiCad Rev 9.0

Logo

Project: RPI CMx Carrier	Drawn by: Jean-Francois Bilodeau	Sheet Size: A3
Sheet Title: rpi_cm4_cm5_CarrierBoard.kicad_pcb	Approved by: Not applicable	Sheet: 15 of 15
Date: 2026-02-15	BOM:	Status: Review
		Current Revision: 2.00-0A